IN THE SPECIFICATION

Please amend the paragraph on page 1, beginning on line 22 as follows:

FIG. 1 is an exploded perspective view of a general photo-receiver module including a general submount for an opto-electronic module. Referring to FIG. 1, a submount 104, to which an opto-electronic device 102 such as a photodiode sticks, is attached to a substrate 106. The submount 104 electrically connects the opto-electronic device 102 to an electronic device (not shown) on the substrate 106 using wires or ribbon bonding. A plurality of signal lines 108 are installed on the substrate 106 for such electrical connection. An amplifier ~~106~~110 for amplifying an electrical signal output from the opto-electronic device 102 to a predetermined level or above is attached to the substrate 106. The amplifier 110 electrically contacts the plurality of signal lines 108 on the substrate 106. The substrate 106, to which the submount 104 and the amplifier 110 are attached, is put into a metal shield case 112 and then the metal shield case 112 is covered with a cover 113. An optical fiber 114, which forms a path of light incident on the opto-electronic device 102, penetrates through the metal shield case 112 and is aligned with the opto-electronic device 102 so that light is properly incident on the opto-electronic device 102. For this, a fiber support 116 is attached to the substrate 106 to support the optical fiber 114.